

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.26
			<b>Subtotal</b>	<b>0.01</b>	<b>100</b>	<b>0.26</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.21	100.0	4.8
			<b>Subtotal</b>	<b>0.21</b>	<b>100</b>	<b>4.8</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.18	100.0	4
			<b>Subtotal</b>	<b>0.18</b>	<b>100</b>	<b>4</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.18	90.0	4.02
	Tin alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0	0.5	0.02
	Tin alloy	Silver (Ag)	7440-22-4	0	2.5	0.11
	Tin alloy	Antimony (Sb)	7440-36-0	0.01	7.0	0.31
			<b>Subtotal</b>	<b>0.19</b>	<b>100</b>	<b>4.46</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.66	100.0	15
			<b>Subtotal</b>	<b>0.66</b>	<b>100</b>	<b>15</b>
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.36
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.11	1.34
	Copper alloy	Copper (Cu)	7440-50-8	53.27	99.86	1213.3
			<b>Subtotal</b>	<b>53.35</b>	<b>100</b>	<b>1215</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0	0.03	0.1
	Copper alloy	Iron (Fe)	7439-89-6	0.02	0.11	0.37
	Copper alloy	Copper (Cu)	7440-50-8	14.55	99.84	331.47
	Copper alloy	Silver (Ag)	7440-22-4	0	0.02	0.07
			<b>Subtotal</b>	<b>14.57</b>	<b>100</b>	<b>332.01</b>
Mould Compound		Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.18	0.7	4.04
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.52	6.0	34.62
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.04	12.0	69.24
	Filler	Silica fused	60676-86-0	17.73	70.0	403.9
	Carbon Black	Carbon black	1333-86-4	0.08	0.3	1.73
	Filler	Misc. Silica compounds (generic)	14808-60-7	2.53	10.0	57.7
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.25	1.0	5.77
			<b>Subtotal</b>	<b>25.33</b>	<b>100</b>	<b>577</b>
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0	0.1	0.1
	Copper alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.82	91.6	87.02
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04	0.9	0.85
	Copper alloy	Molybdenum (Mo)	7439-98-7	0.29	7.0	6.65
	Copper alloy	Manganese (Mn)	7439-96-5	0.02	0.4	0.38
			<b>Subtotal</b>	<b>4.17</b>	<b>100</b>	<b>95</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.07	5.0	1.5
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.75
	Lead alloy	Lead (Pb)	7439-92-1	1.22	92.5	27.75
			<b>Subtotal</b>	<b>1.32</b>	<b>100</b>	<b>30</b>
			<b>Total</b>	<b>99.99</b>	<b>100</b>	<b>2277.53</b>

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